

SOT643-1

plastic low profile fine-pitch ball grid array package; 81 balls;
body 9 x 9 x 1.05 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA81
Package type industry code	LFBGA81
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	28-3-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.9	-	9	9.1	mm
E	package width	8.9	-	9	9.1	mm
A	seated height	[tbd]	-	1.6	1.6	mm
A ₂	package height	0.95	-	1.05	1.2	mm
n ₂	actual quantity of termination	-	-	81	-	



2. Package outline

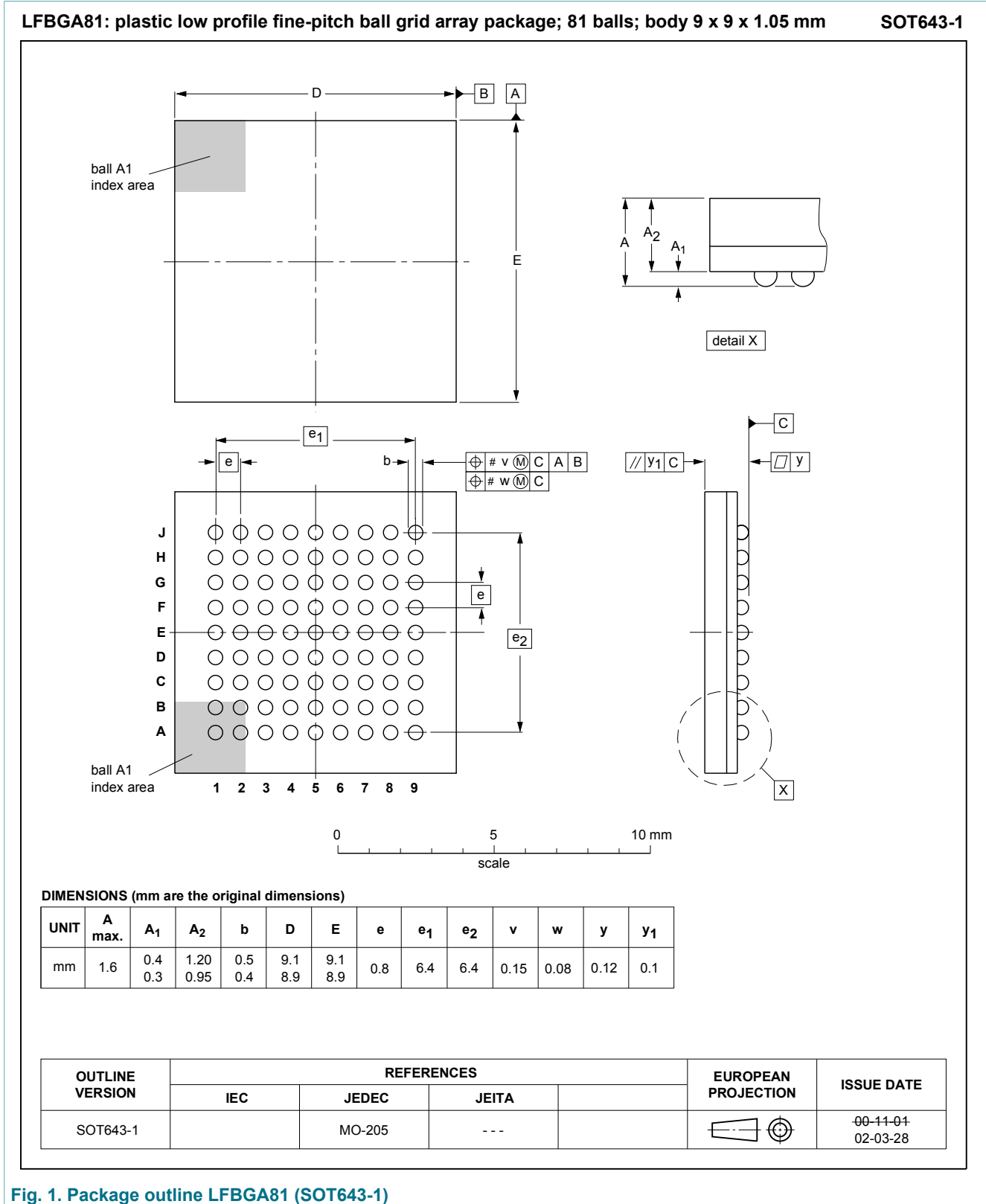


Fig. 1. Package outline LFBGA81 (SOT643-1)

3. Soldering

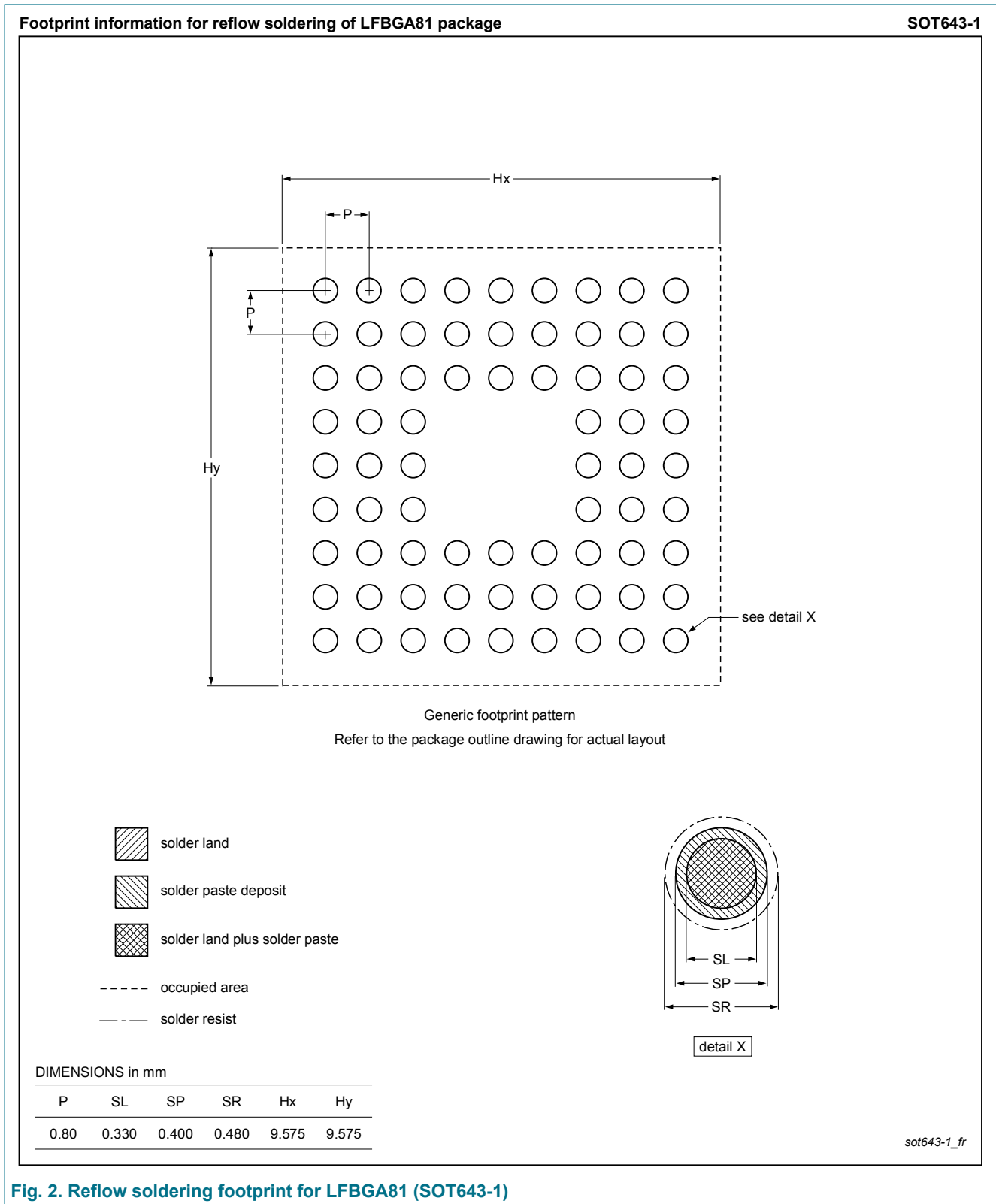


Fig. 2. Reflow soldering footprint for LFBGA81 (SOT643-1)

4. Legal information

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